

20. (New) A method as claimed in claim 19 including completely melting the plurality of metal powders in a single reflow step.

21. (New) A method as claimed in claim 17 including completely melting the plurality of metal powders in the reflow soldering.

c) 22. (New) A method as claimed in claim 21 including completely melting the plurality of metal powders in a single reflow step.

23. (New) A method as claimed in claim 18 including heating the solder paste to completely melt the plurality of metal powders.

24. (New) A method as claimed in claim 23 including completely melting the plurality of metal powders in a single reflow step.

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REMARKS

In this amendment, new claims 19 - 24 have been added to describe additional features of the present invention. Claims 19, 21, and 23 state that the method of claim 16, 17, or 18 includes completely melting a plurality of metal powders, and claims 20, 22, and 24 state that the method of claim 16, 17, or